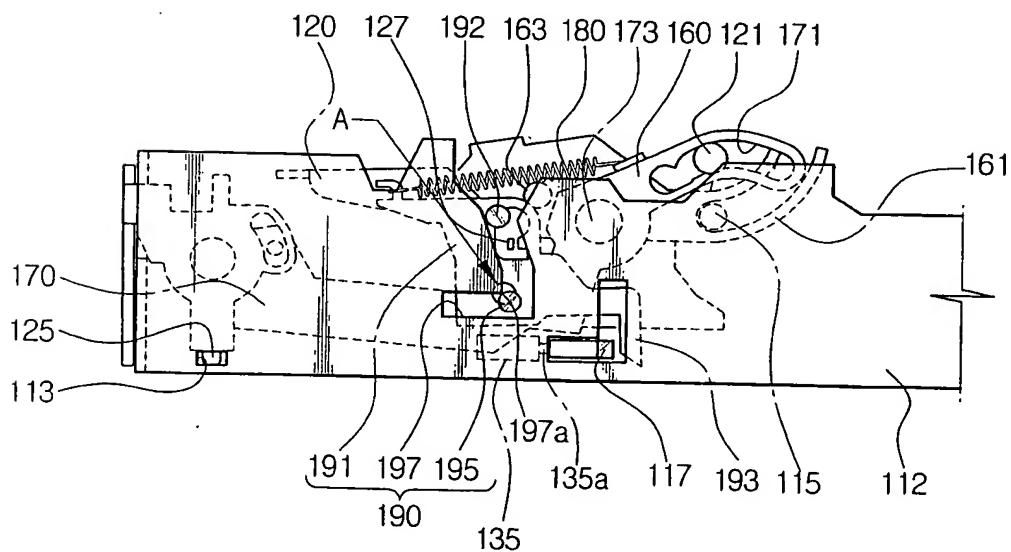
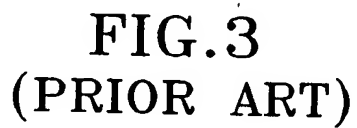


This diagram shows an exploded perspective view of a multi-layer printed circuit board assembly 100. The assembly includes a top layer 120, a middle layer 165, and a bottom layer 150. A central component 130 is positioned between the middle and bottom layers. The bottom layer 150 features two circular openings 111 and 112, which are part of a larger structure 110. A component 113 is located near these openings. A bracket 115 indicates a section of the bottom layer. A component 117 is also shown. A component 140 is positioned on the right side of the bottom layer. A bracket 190 groups components 191, 195, and 197. A component 197a is also indicated. Other components shown include 121, 125, 127, 163, 161, 160, 170, 171, 173, 180, and 192.

FIG.2
(PRIOR ART)



ORIGINAL

FIG. 4
(PRIOR ART)

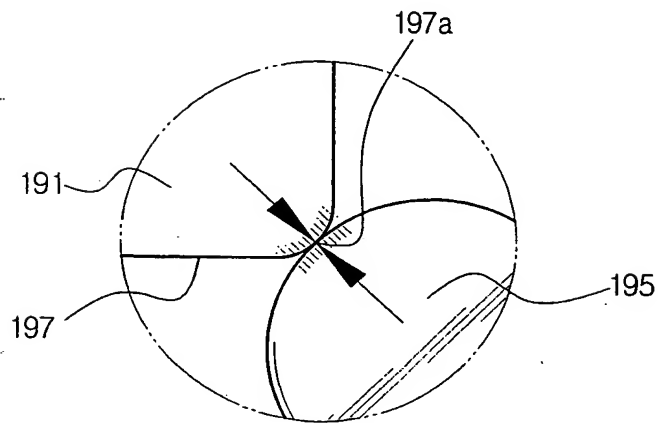
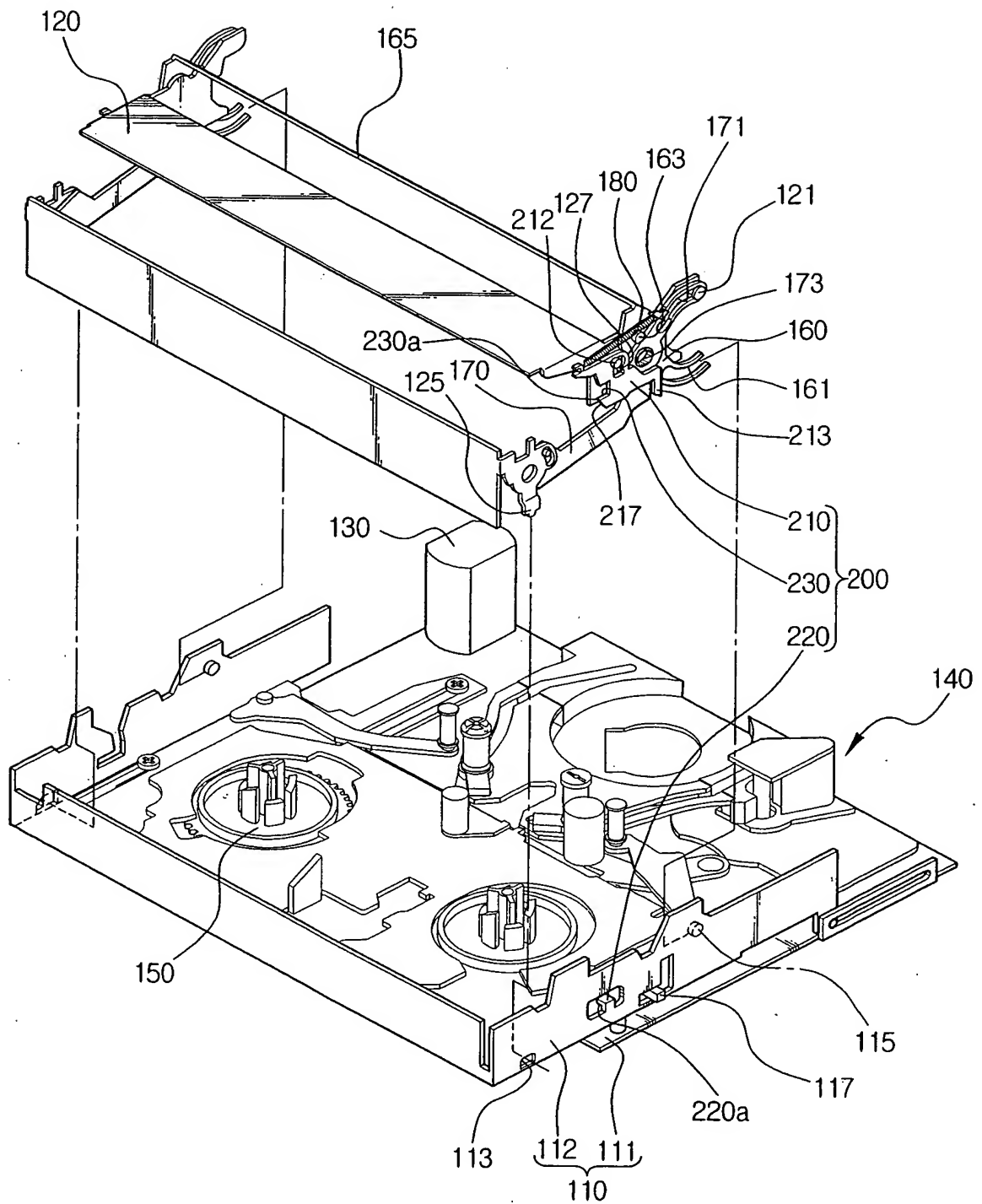


FIG. 5

100



ORIGINAL

FIG.6

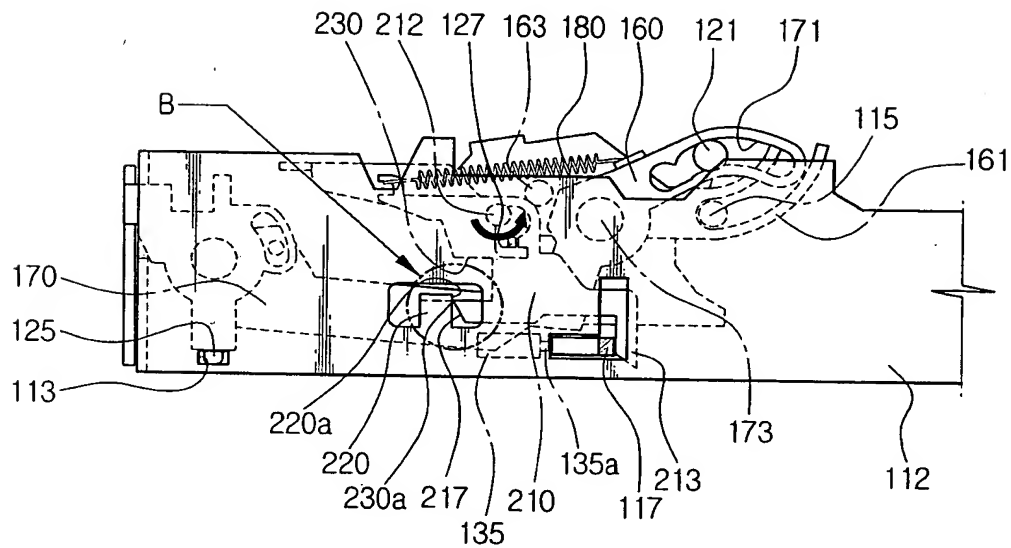


FIG. 7

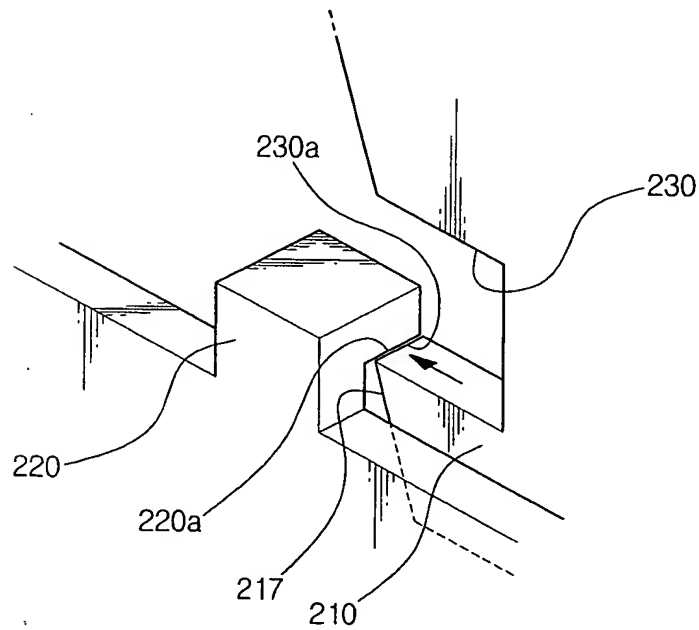


FIG.8

100

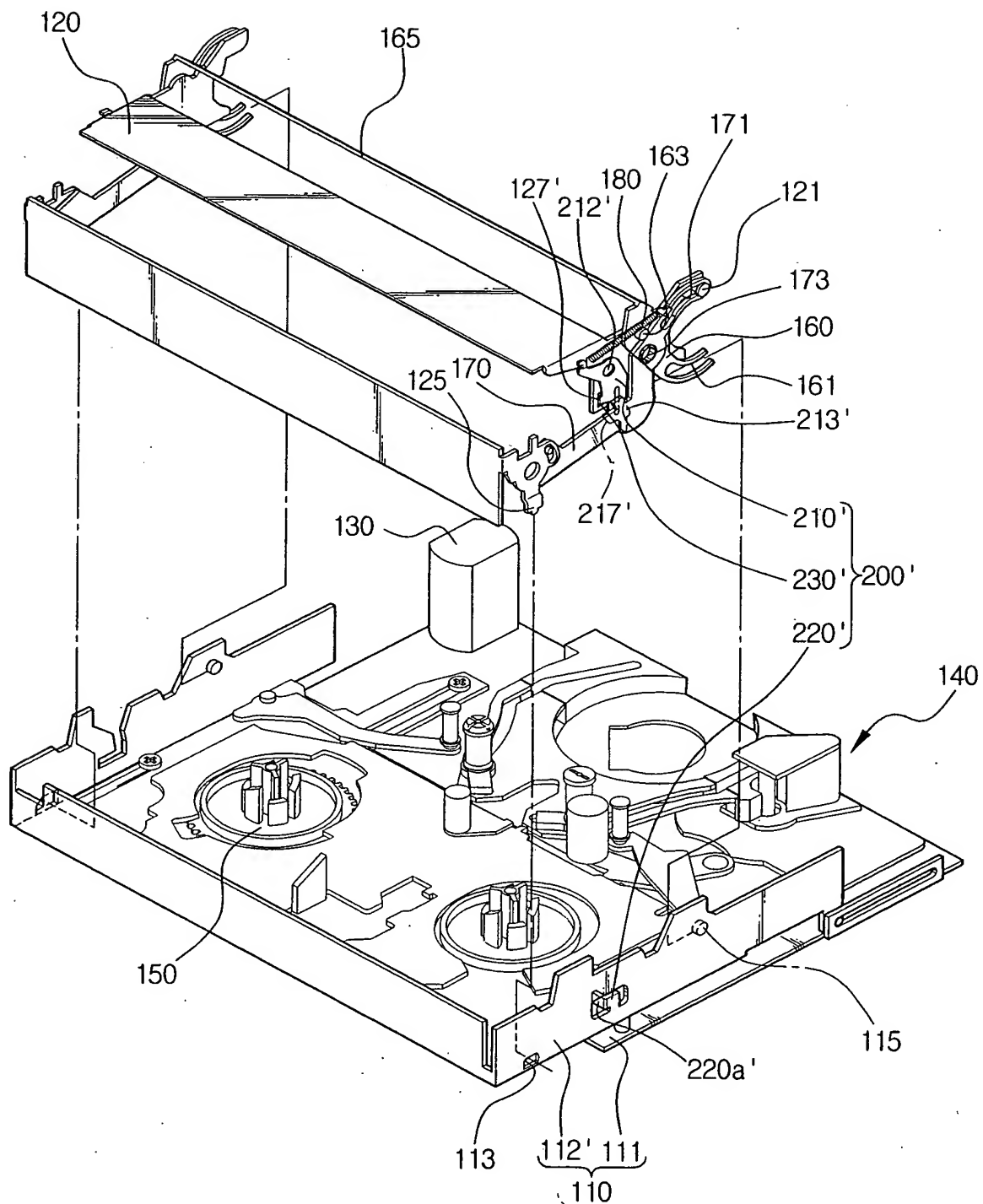


FIG.9

